

Issue 01

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forres.eu



@ForRES_HEU



ForRES-HEU

Project Coordinator

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Coordination Support

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Technikon

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Budget

€ 2.3 Million

90% EU-funded



Consortium

5 Partners

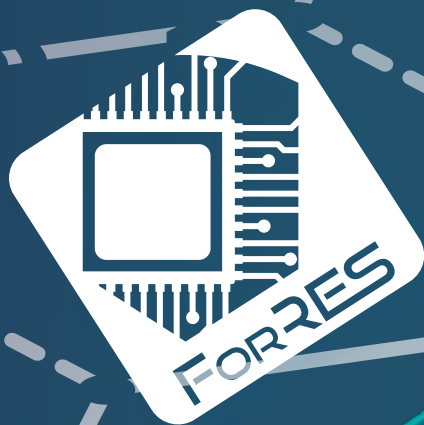
5 countries



Duration

24 Months

07/2023 - 06/2025



Forensic Reverse Engineering of Silicon Chips

Advanced digital investigation
to tackle cybercrime of
electronic devices

Welcome message from the coordinator

The intention of this newsletter is to open a new communication channel to provide news on the project progress and to discuss ongoing topics relevant to ForRES. This newsletter is directed towards internal and external project partners, stakeholders, and all other interested bodies. As we move forward, we remain com-

mitted to achieving our objectives and making significant contributions to the field of digital forensics. Thank you for your continued support and dedication.

Best regards,

Jürgen Frinken



Main goals

ForRES is dedicated to overcoming the challenge posed by encrypted consumer devices faced by European law enforcement agencies. Its primary aim is to improve techniques for analysing integrated circuits, fostering collaboration between European LEAs and scientific institutions. The project, which runs for

24 months from July 2023, receives substantial funding from the EU. Key objectives include enhancing the operational capabilities of European forensic science institutes, conducting invasive methods on semiconductor devices in a common workflow and creating a platform for collaborative knowledge sharing.

Status update

After the initial 8 months, ForRES has achieved notable progress across various fundamental areas. The project has successfully identified target chips and conducted thorough analyses of their composition, laying the foundation for further examinations. In the first work package, a common framework for working on these chips has been established, fostering efficient collaboration among consortium members.

In subsequent work packages, ForRES has advanced in pinpointing the semiconductor chip technologies to prioritize, focusing on those most aligned with the project's goals. This targeted approach optimizes resource allocation and enhances

the impact of the research efforts.

Moreover, the project has actively engaged in dissemination activities, including presentations at pertinent conferences and workshops. These initiatives have actively communicated ForRES's objectives and accomplishments to the scientific forensic community and relevant stakeholders, bolstering awareness and support for the project.

Overall ForRES continues to progress steadily towards its objectives, marked by significant advancements in chip identification, technology determination, and dissemination endeavours.

The ForRES Consortium

The ForRES consortium consists of 5 partners from 5 different countries (Germany, Austria, The Netherlands, Spain and Norway). It includes leading organisations from the different industry domains in

automated trust management and security, different stakeholders in the supply chain complemented by expertise from the research sector and SMEs.



Bundeskriminalamt (BKA)
Germany [Wiesbaden]



Technikon Forschungs- und
Planungsgesellschaft mbH
Austria [Villach]



Netherlands Forensic
Institute
Netherlands [The Hague]



Agencia Estatal Consejo
Superior de Investigaciones Científicas
Spain [Barcelona]



Politidirektoratet
Norway [Oslo]



Past Events

Forensic Experts Forum 2023

14th-15th September 2023
@The Hague, Netherlands

Kick-off Meeting

18th September 2023
@Wiesbaden, Germany

Annual Forensic Silicon Experts Meeting

19th-22nd September 2023
@Wiesbaden, Germany



Upcoming Events

Hardware Reverse Engineering Workshop (Harris 2024)

19th-20th March 2024
@Bochum, Germany

Annual Forensic Silicon Experts Meeting

23rd September 2024
@Barcelona, Spain

All past and upcoming events can be found on the ForRES official webpage:

forres.eu/events



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